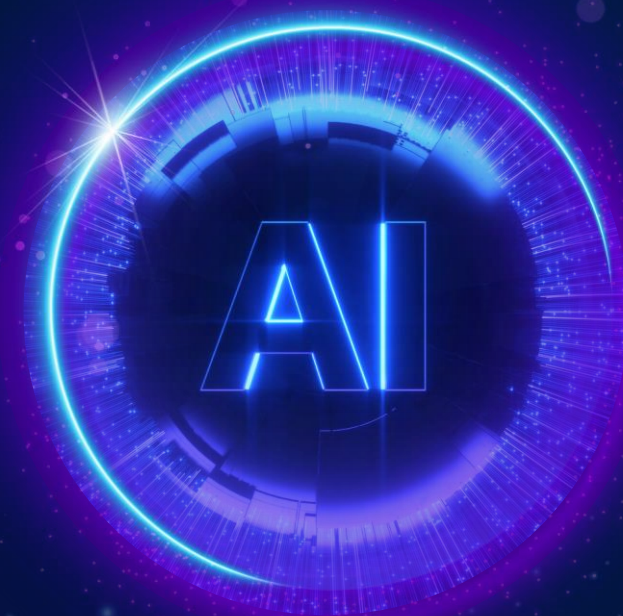


# Artificial Intelligence Executive Conference

*explore the power of AI to transform semiconductor design & manufacturing*

**Presentation**  
**AI, the next evolution of PDF Solutions portfolio**

**John Kibarian**  
CEO, PDF Solutions



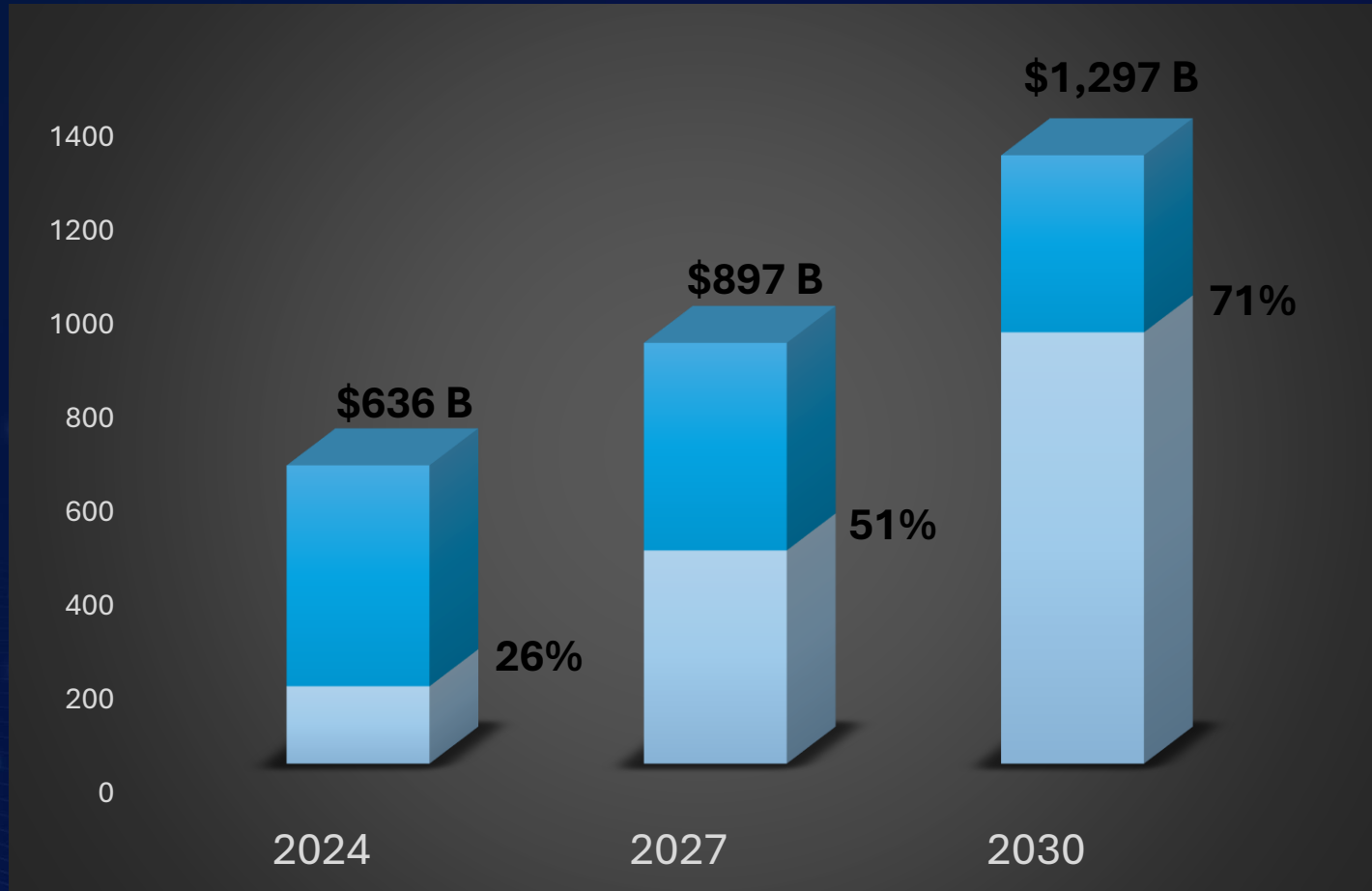
*This presentation and discussions resulting from it may include future product features or fixes, or the expected timing of future releases. This information is intended only to highlight areas of possible future development and current prioritizations. Nothing in this presentation or the discussions stemming from it are a commitment to any future release, new product features or fixes, or the timing of any releases. Actual future releases may or may not include these product features or fixes, and changes to any roadmap or timeline are at the sole discretion of PDF Solutions, Inc. and may be made without any requirement for updating. For information on current prioritizations and intended future features or fixes, contact [sales@pdf.com](mailto:sales@pdf.com).*

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AI is driving semiconductor revenue growth.

AI related devices will represent 71% of total semiconductor revenue in 2030



How do we use Analytics and AI to help the industry efficiently deliver on this opportunity?

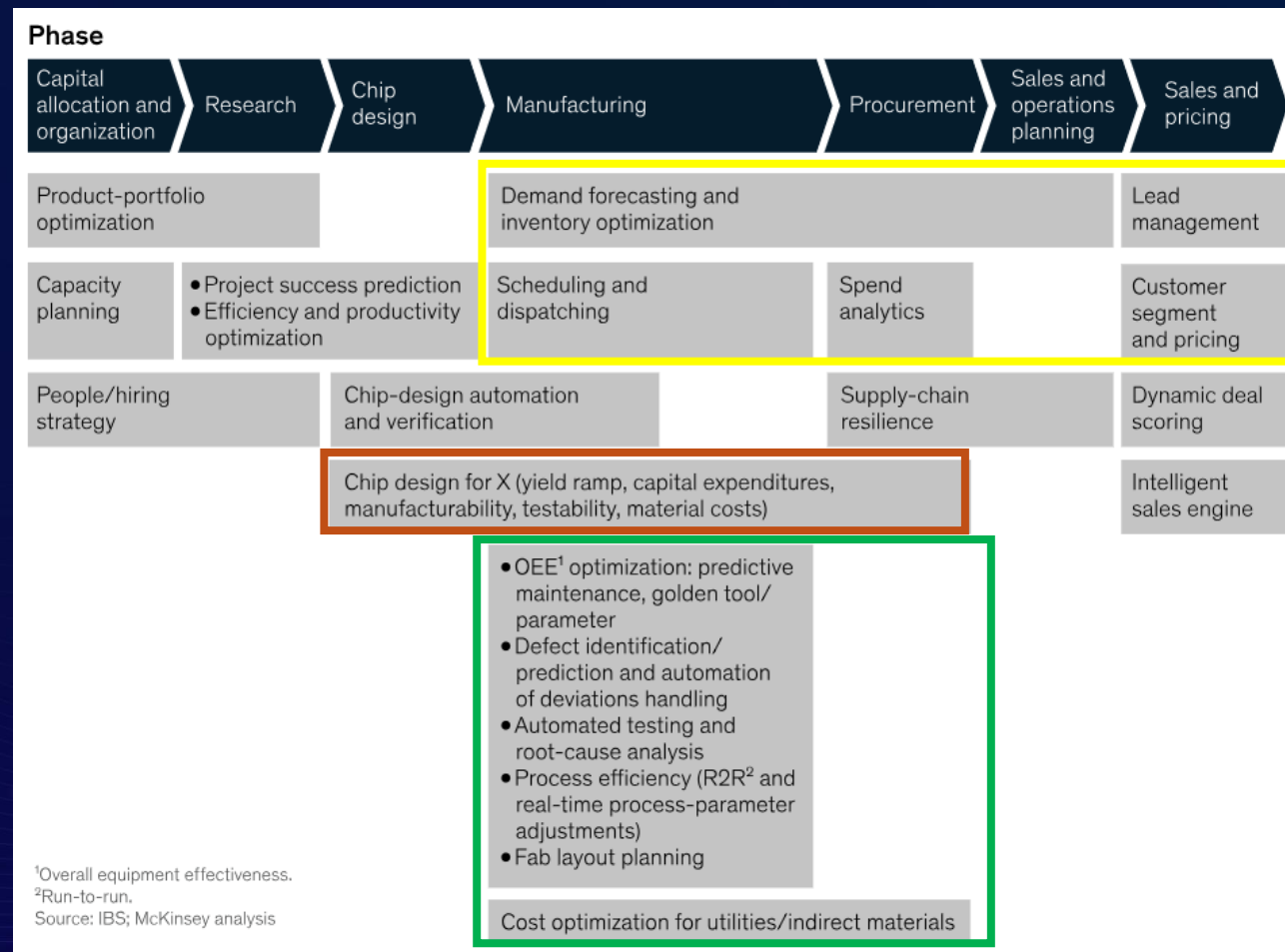
Source: BIS 2024

# AI/ML use cases in the semiconductor industry

AI/ML currently contributes between \$5 billion and \$8 billion of annual earnings at semiconductor companies

This figure could potentially rise to between \$85 billion to \$95 billion per year in the long term, equivalent to about 20% of the industry's current annual revenue

- Manufacturing Efficiency
- Chip / Process Design
- Supply Chain Integration



Source: McKinsey 2021

# How can we scale AI /ML and move beyond the daily support of the knowledge worker?

*“One problem is **messy data**, scattered in different formats across departments and systems. “Single source of truth” - the company had 37. A **failure to organize data** before using it to train increases the risk of hallucinations and mistakes”*

*“It’s very easy to build impressive POCs. A lot of people have got stuck in that trap. **The challenge emerges when you try to translate to production.** There is a huge gap between early POCs and production”*

*“Transforming into a digital firm requires changing operating architectures and align around a platform approach”*

*“A large Japanese semiconductor company with tens of thousands of employees has 30 employees with the know how to use AI/ML. **For AI to have an impact, it must be pervasive**”*

**DATA**

**SCALING**

**AUTOMATION**

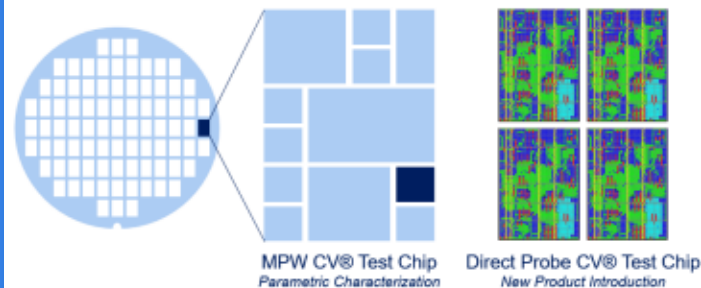
**SKILLS**

# The Transformation of PDF Solutions

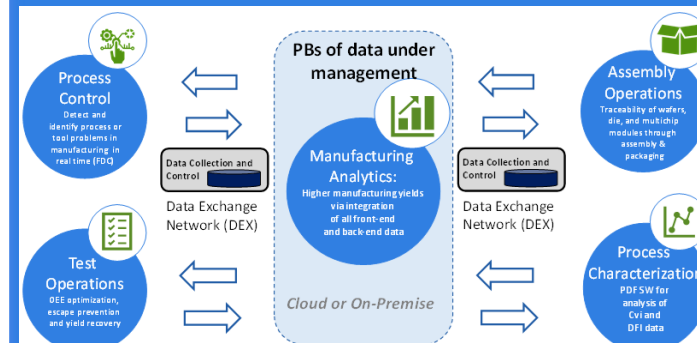
PDF Solutions has consistently anticipated the evolution of the industry and developed new scalable analytics capability

## Yield Ramp Characterization Vehicle

### CV System for Fabless



## High Volume Manufacturing Analytics



## AI-driven 3DIC test solutions

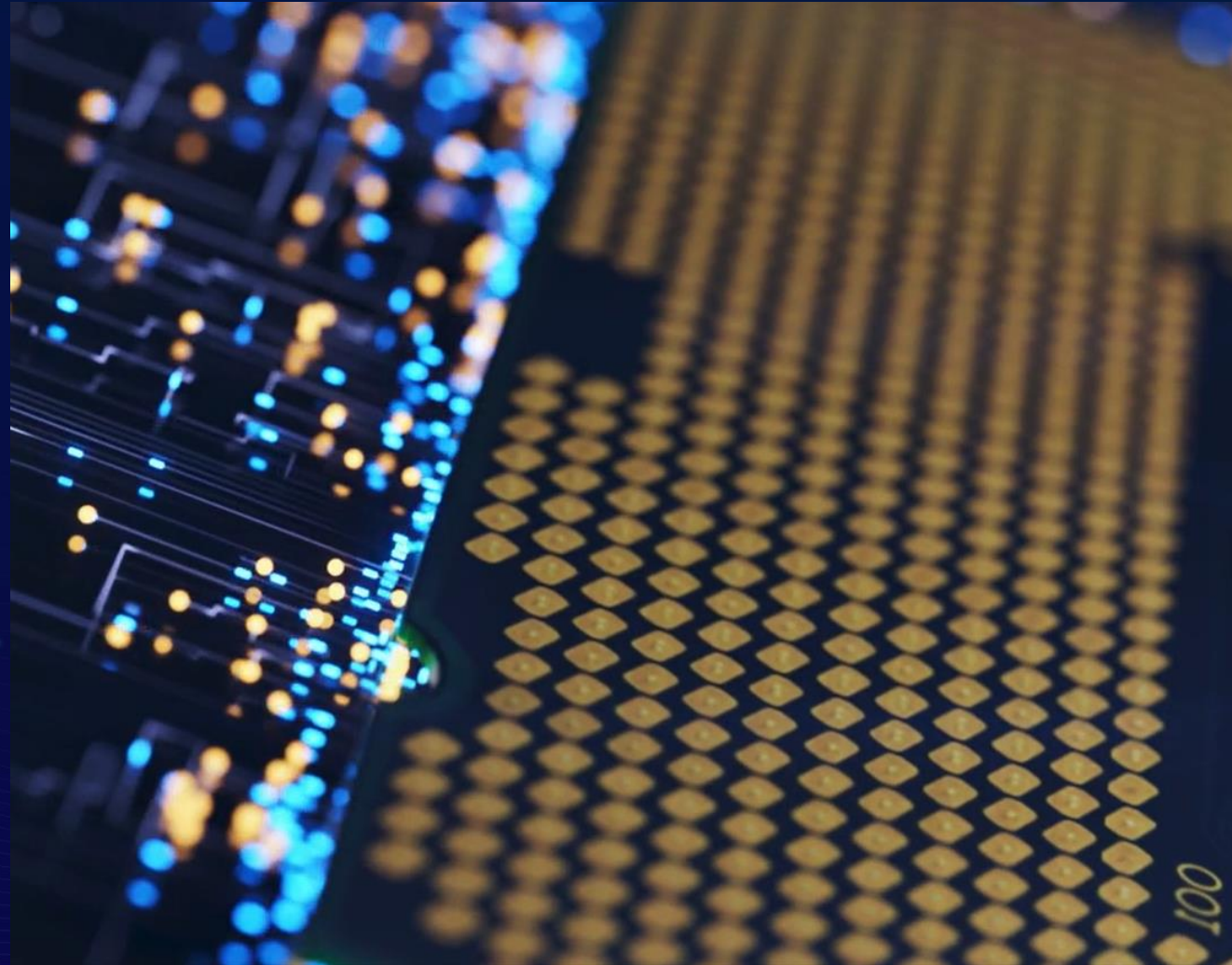


## Our approach to scaling AI /ML in our solutions

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AI solutions for large-scale semiconductor deployments need to be built with 3 main design principles

- 01 Data Infrastructure & Semantic
- 02 AI Enabled Decision Making
- 03 Enterprise Scale Solutions

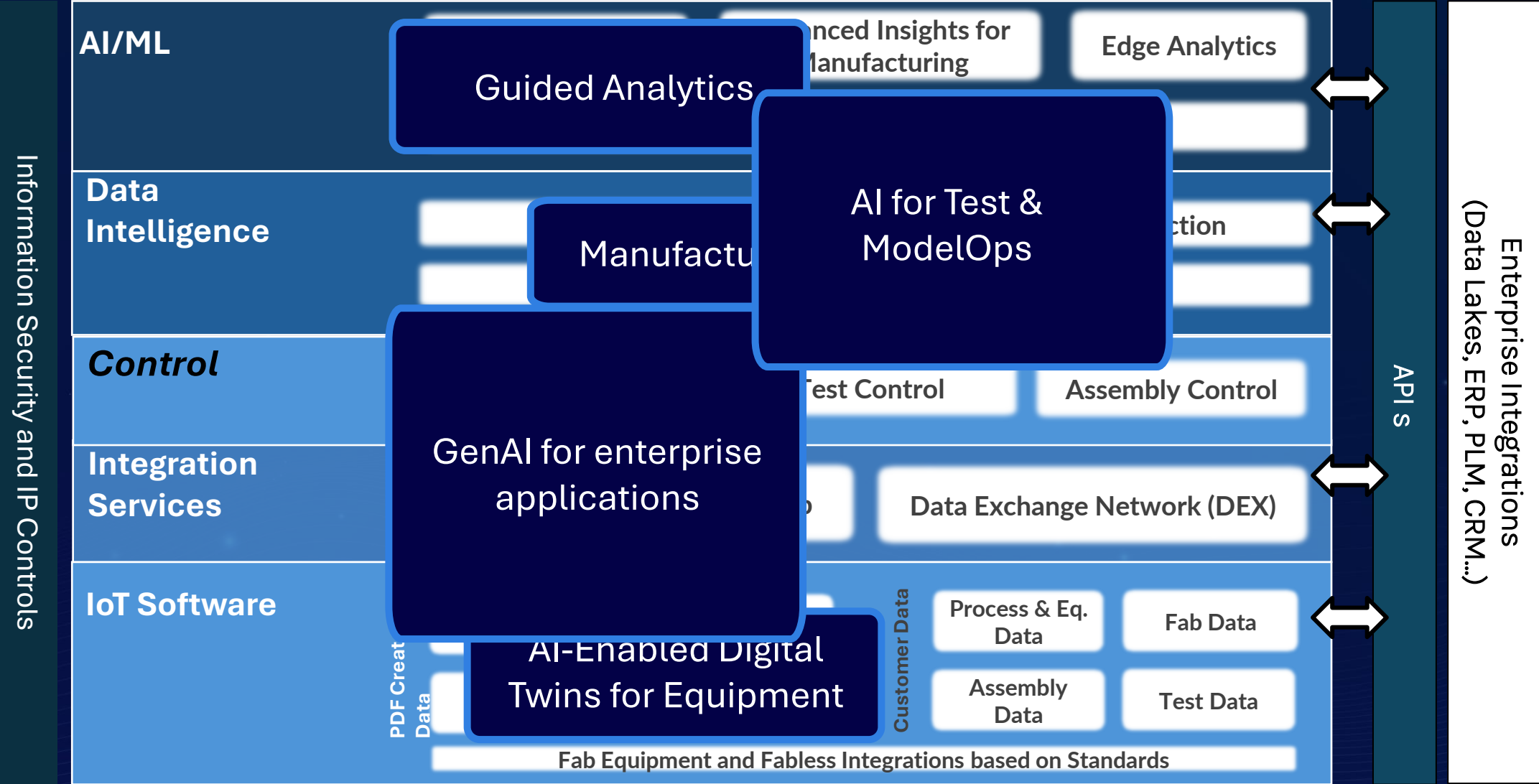


## Tangible applications of AI in semiconductor industry

Today we are presenting a series of AI enabled solutions all built on the overall PDF Solutions platform

	Manufacturing Data Lakehouse	Guided Analytics	AI-Enabled Digital Twins for Equipment	AI for Test & ModelOps	GenAI for enterprise applications
Data Infrastructure & Semantic					
AI Enabled Decision Making					
Enterprise Scale Solutions					

# AI enabled solutions are built on the PDF Solutions platform

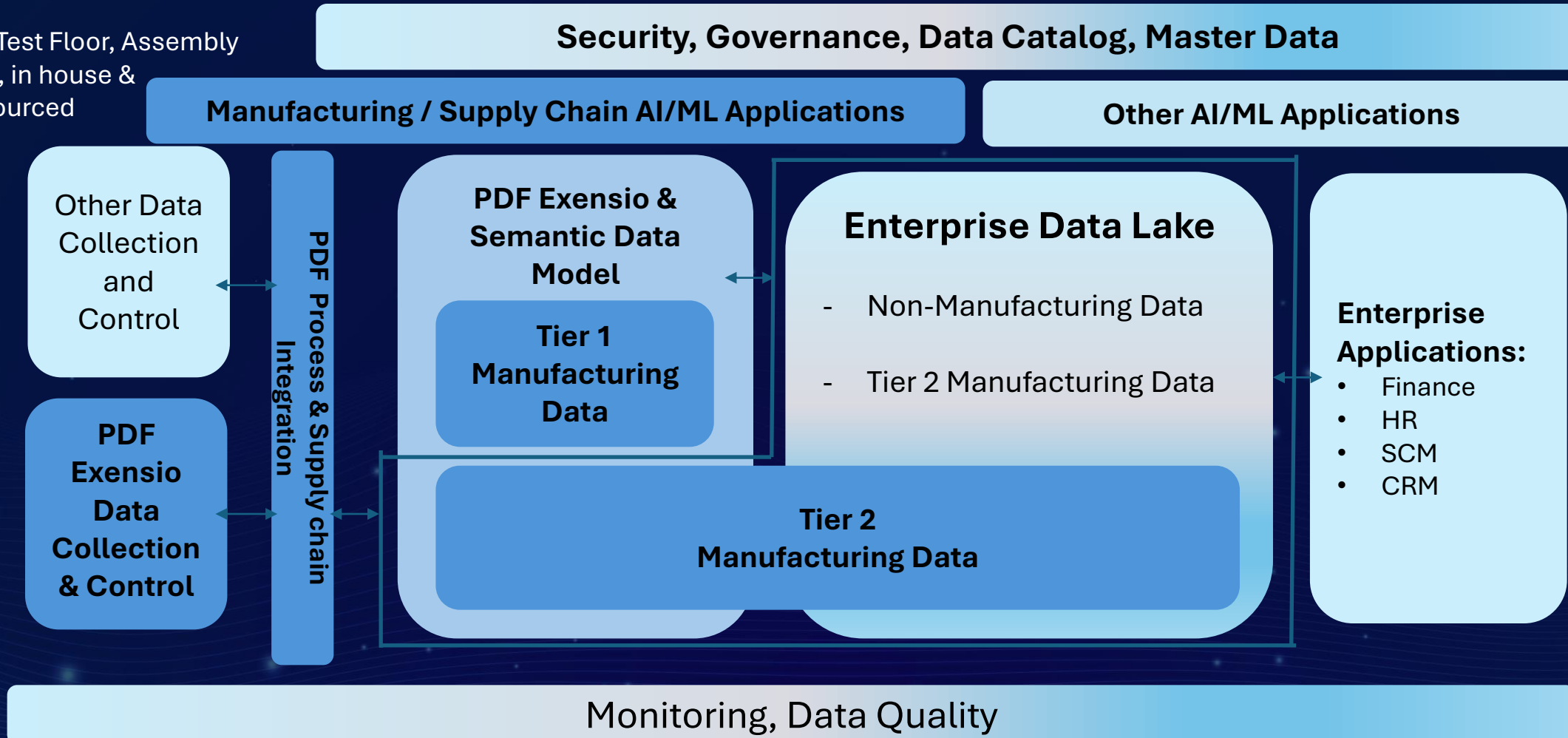


# Manufacturing Data Lakehouse

Manufacturing Data  
Lakehouse

PDF Solutions Exensio is the foundation to align manufacturing data across the enterprise

Fab, Test Floor, Assembly  
Floor, in house &  
outsourced



Extremely large and complex data sets

80% of the time of the data analysts is spent in data wrangling and querying activities



2 PB of Data

Exensio Cloud Hosted Data:

4 times as much as the entire Spotify music library or the equivalent of a 1000 years of non-stop HD movie streaming...



Automatically summarizes data and run diagnostics

For 2000 products: Wafer sort (includes die bins, Parametric test), final test (die bins, Parametric test), PCM data, info on test equipment used, site and retest information

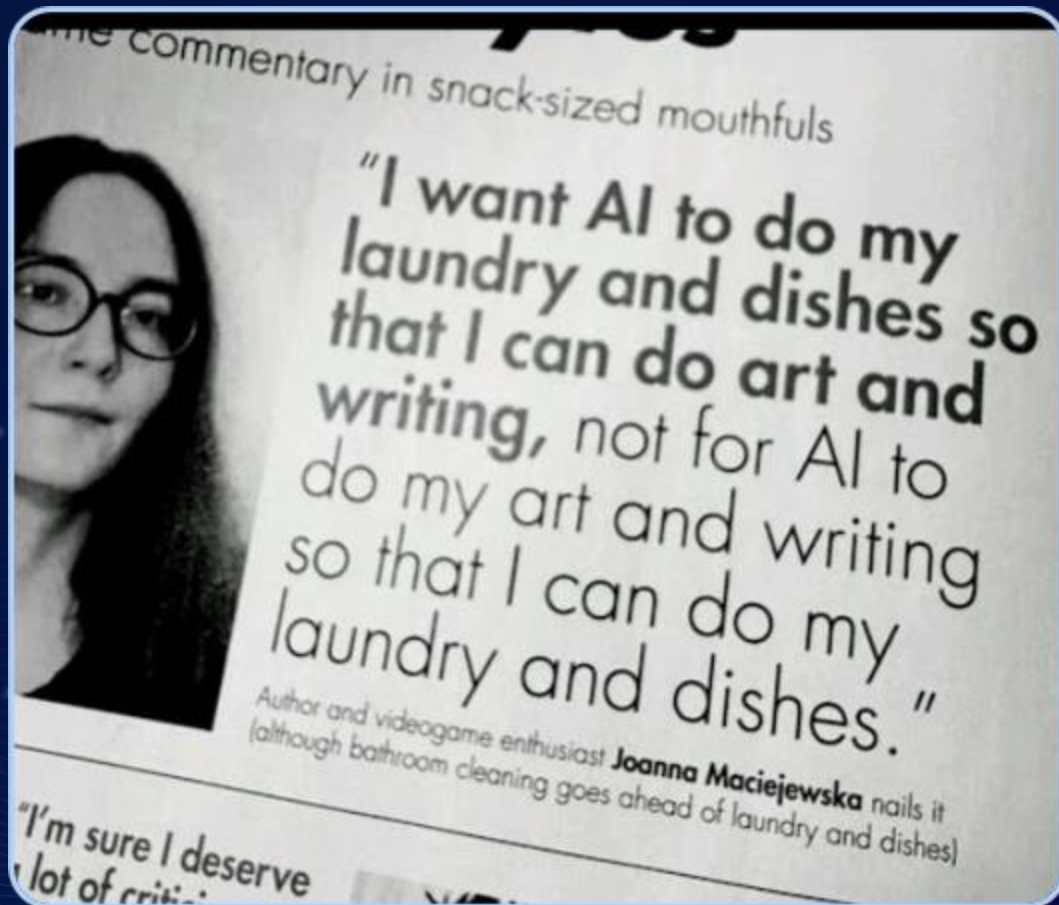


Up to 1M columns & 5M rows

Large Exensio Manufacturing Analytics deployment

## Transforming user experience

With AI there is an opportunity to dramatically transform the experience of the users and create new modes of decision making when dealing with extremely large and complex data sets



data



infrastructure



model

## Guided Analytics

Mine all the data continuously, identify issues, guide users to resolutions

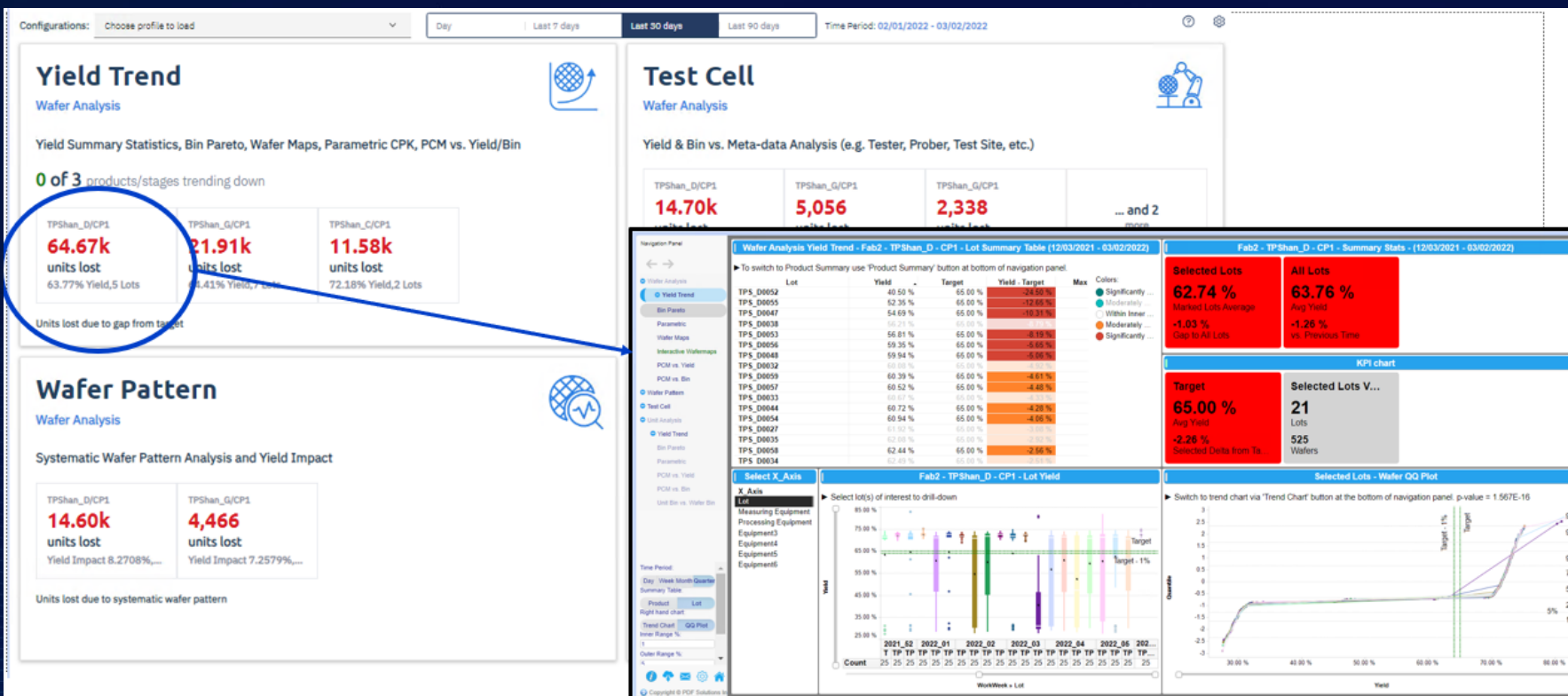
1. Automated advanced ML identifies failure signals and associated root causes
2. Ultra-fast performance
3. Analyze all your data types daily, Continuously mine 100% of your data

Greatly simplifies and reduces engineering effort

- Signals
  - Low Yield, Mid Yield
  - Excursions
  - Bin\_Pattern (e.g. Bin15\_edge)
- Root causes
  - PCM/WAT (WS)
  - Test Cell Tools (WS/FT)

Executive dashboard highlights relevant results across all products

Easy to understand dashboard with very few clicks required



## Why Digital Twin?

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### 01 Development

- Virtual prototyping
- Collaborative design

### 02 Manufacturing

- Equipment characterization
- Chamber matching
- Reduce fleet variability

### 03 Servicing

- Predictive failure analysis
- Enhance services opportunities



## AI-Enabled Digital Twins for Equipment

AI-Enabled Digital  
Twins for Equipment

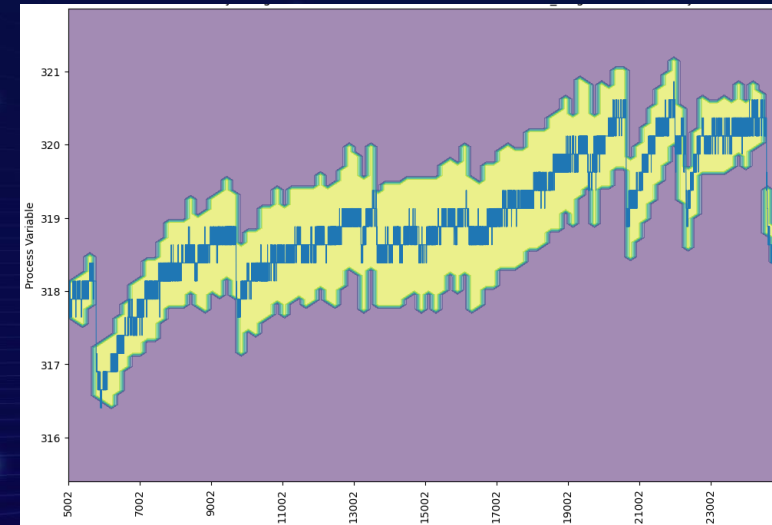
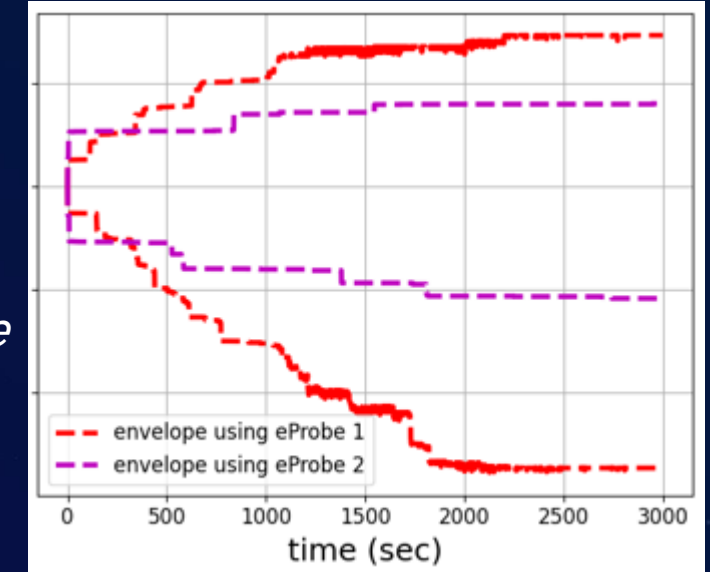
1. Provides a Higher Level of Equipment Reliability and Deeper Visibility into Equipment Performance
  - Ability to Check Overall Equipment Health
    - Overall Equipment Health & Characterization
    - Monitor Critical Equipment Sub-Component's Health
    - Create Golden Fingerprints for Each Sub-Component
  - Predict Failures Before They Happen
    - AI/ML Monitors and Identifies When Component Health Starts to Deteriorate Over Time
    - Prevents Costly Unscheduled Tool Downtime
2. Enables a new flow of recurring revenue from services contracts



PDF Solutions is scaling the deployment of its eProbe solution with an AI driven support services capability

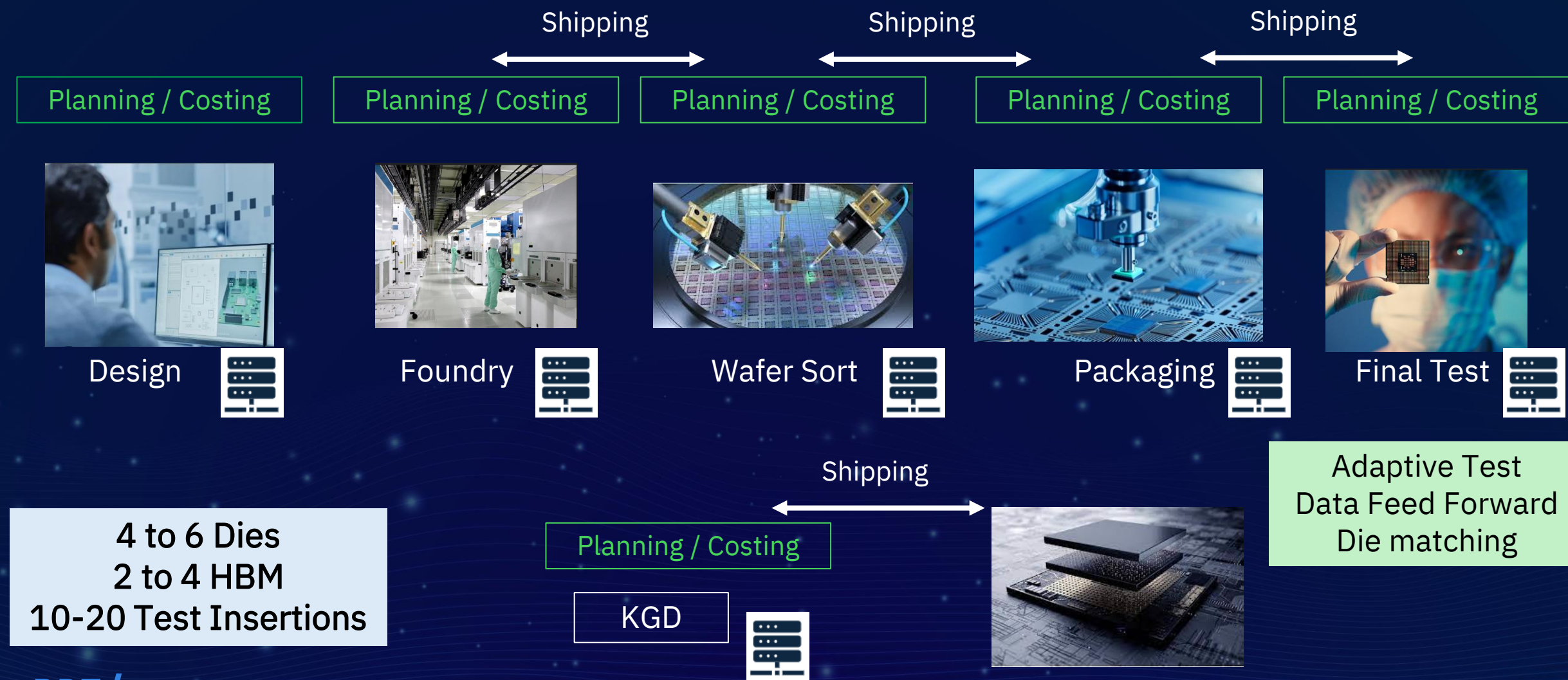


*Predict tip quality as measured by the variability of Emission current as a function of Heating current using “envelope modeling”*



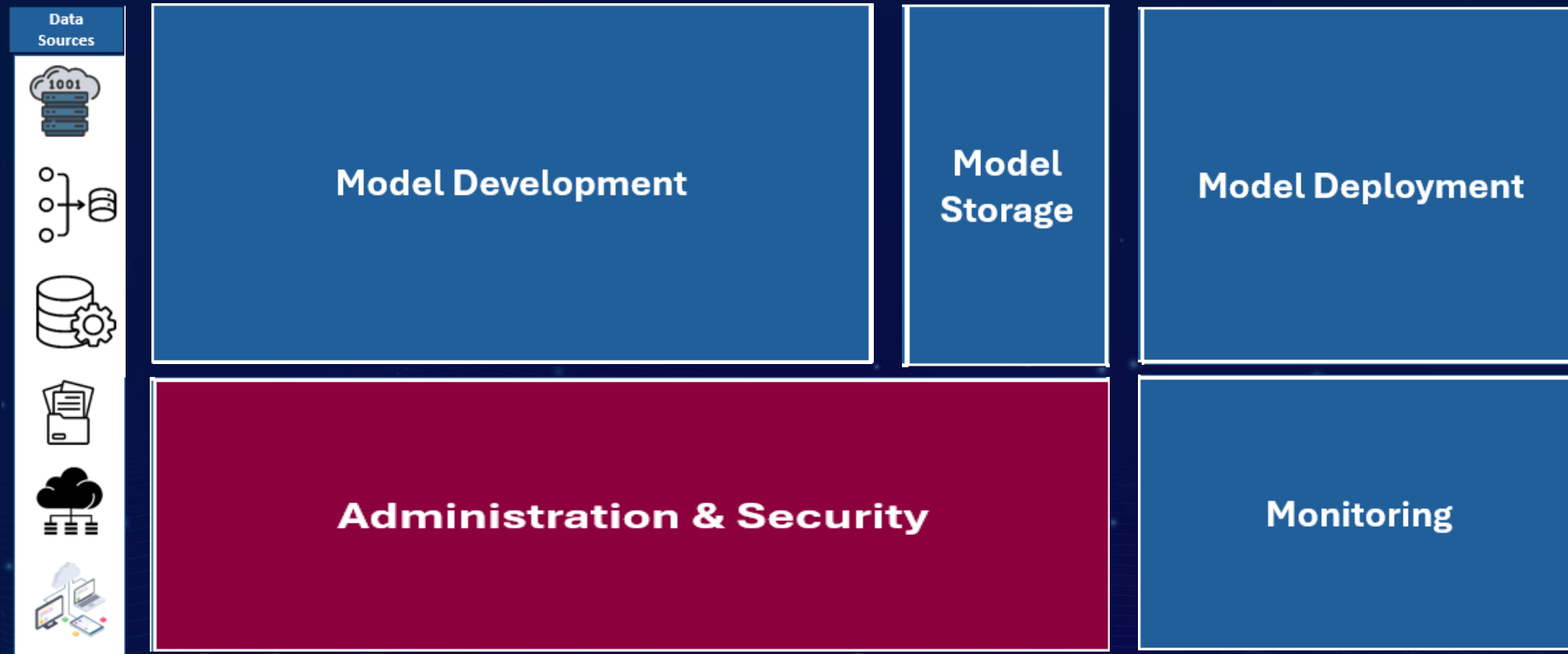
# Testing hybrid devices across a globally distributed supply chain calls for an integrated approach

AI for Test & ModelOps

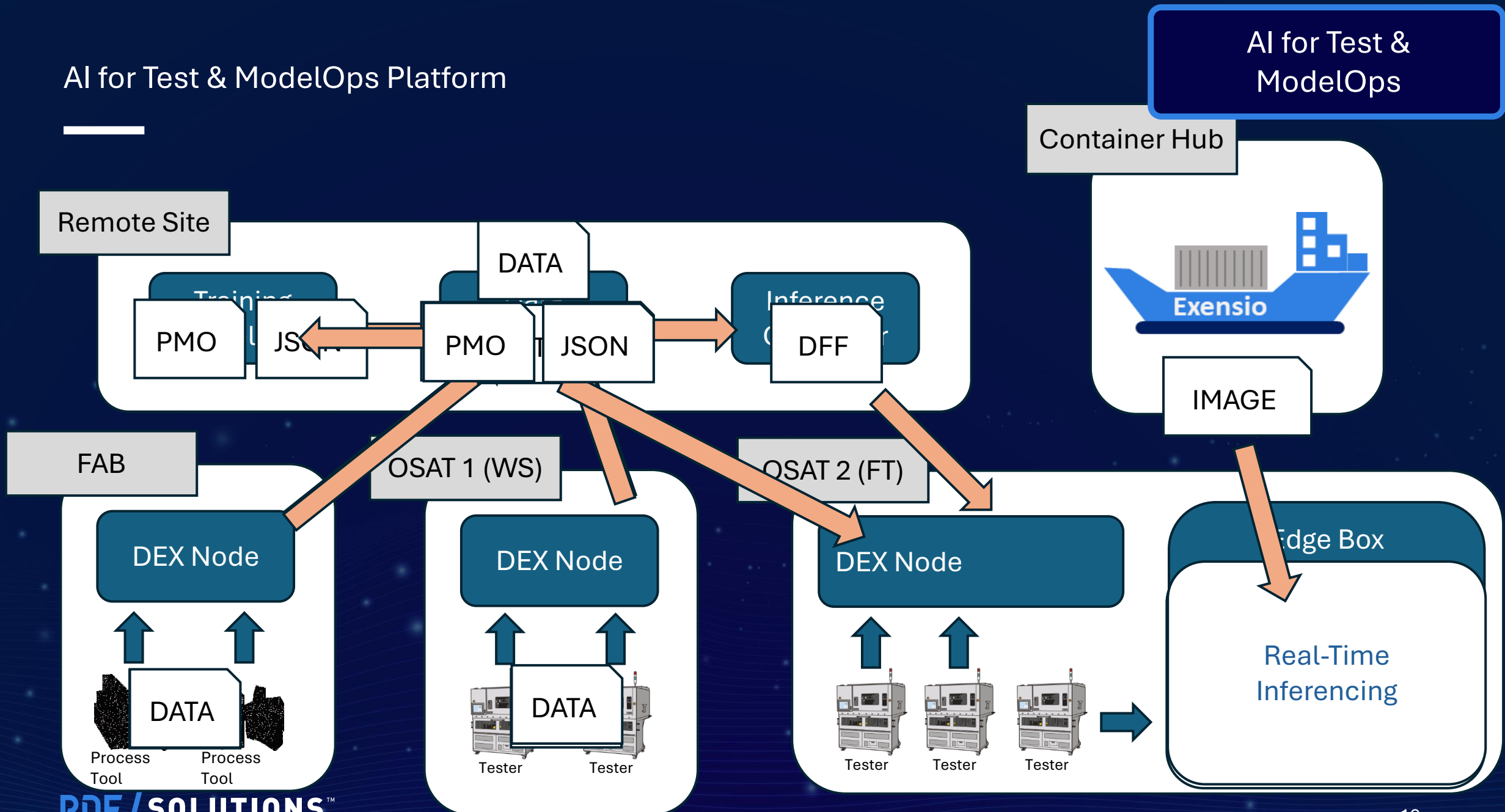


## Create, Manage and Control models across their lifecycles

It is not only about the "best model" it is about the platform to support the deployment of various models where they will drive action.



# AI for Test & ModelOps Platform



## Transforming PDF Solutions with GenAI

### PDF Solutions strategy to adopt GenAI

1

Data security and privacy

Virtual Private Cloud (VPC) or on-prem.  
No external API's.

2

Platform with existing LLM models & systems

3

Improving Exensio usability and user experience

4

Better predictive models with less data

The screenshot displays the Exensio GenAI Assistant interface. At the top, the 'User' section shows the company 'Exensio' and the question: 'How do I perform PCM vs. Bin yield correlation for a product?'. The 'Assistant' section shows a progress bar with three steps: 'Analyzing the question', 'Planning document search', and 'Thinking' (marked as 'New'). Below this, the 'Answer' section provides a detailed response. It starts with a summary: 'To perform PCM vs. Bin yield correlation for a product, use Product Sensitivity Analysis (PSA) to retrieve site-level data, configure appropriate parameters, and analyze the correlations through statistical methods and visualization tools.' This is followed by a step-by-step process: 1. Initial Data Retrieval (with sub-steps: Launch the data retrieval tool (2), Select 'Raw' from Load Level drop-down menu, Choose appropriate PCM and binning programs, Ensure Program index is loaded with retrieval), 2. Configure PSA Analysis (with sub-steps: Define Input Arguments (4): Select source data table, Enter site columns expression for PCM parameters (X-axis), Enter sort columns expression for bin data (Y-axis); Set Analysis Parameters: Choose statistical test (ANOVA or Kruskal-Wallis), Select best fit method (Linear), Define number of groups (typ)), and 3. Set Filtering Criteria (5). The interface includes navigation controls like up/down arrows and a plus sign, and a 'Selected Topics' section at the bottom right showing 'Exensio'.

## SAP and PDF AI Solutions Summary

### Gen AI use cases that are most valuable based on customer feedback



Sapience  
Manufacturing  
Hub



# Scaling AI /ML in Semiconductor Manufacturing

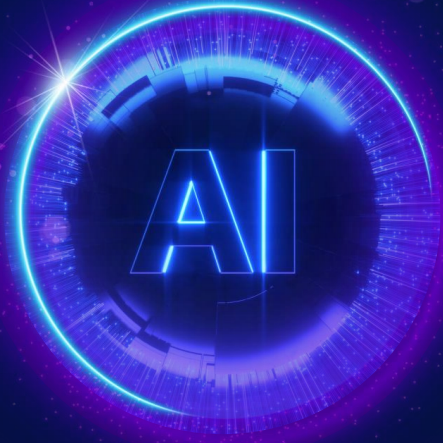
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**DATA**

**SCALING**

**AUTOMATION**

**SKILLS**



# Thank You

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